



PATENT
Attorney Docket No. P106-US

JFeJ

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Terry Tarn

Art Unit: 2826

Serial No.: 10/698,656

Examiner: Victor Mandala

Filed: 10/30/03

For: **DEVICE PACKAGES WITH LOW STRESS ASSEMBLY PROCESS**

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97(b)

Commissioner for Patents
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Alexandria, VA 22313-1450

Sir:

The attention of the Patent and Trademark Office is hereby directed to the following documents:
serial number 10,167,361 to Patel, et al, filed June 11, 2002;

The attention of the Patent and Trademark Office is hereby also directed to the documents listed on the attached PTO form 1449. Copies of the cited references are enclosed.

This Information Disclosure Statement is being submitted after issuance of a first official action on the merits and expiration of the three month period following filing of the above-captioned application, but prior to issuance of either a final official action or a Notice of Allowance.

The above information is presented so that the Patent and Trademark Office can determine any materiality thereof to the claimed invention. It is respectfully requested that the information be expressly considered during the prosecution of this application.

The Commissioner is hereby authorized to charge any additional fee (or credit any overpayment) associated with this statement to our Deposit Account No. 501516.

Respectfully submitted,



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Attorney for Applicant(s)

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Sheet

1

of

4

Complete if Known

Application Number	10/698,656
Filing Date	10/30/03
First Named Inventor	Terry Tarn
Art Unit	2826
Examiner Name	Victor Mandala

Attorney Docket Number P106-US

U.S. PATENT DOCUMENTS

Examiner Initials*	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number- Kind Code ² (if known)			
AA	US- 4,178,077		12-11-1979	TE VELDE	
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Examiner Initials*	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶
		Country Code ³ -Number ⁴ - Kind Code ⁵ (if known)				
BA	EP-1097901-A2		05-09-2001	HA et al.		
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BC	EP-1167281-A2		01-02-2002	KANG et al.		
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BJ	JP-2001196484-A		07-19-2001	JU et al.		

Examiner Signature	Date Considered
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¹ Applicant's unique citation designation number (optional). ² See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

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<p style="text-align: center;">INFORMATION DISCLOSURE CITATION</p> <p>MAR 21 2005</p> <p>PCTO-1449</p> <p><i>Shaw 2 of 6</i></p>		ATTY. DOCKET NO.		SERIAL NO.			
		P106-US		10/698,656			
		APPLICANT Terry Tarn					
		FILING DATE 10/30/03		GROUP 2826			
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
						<input type="checkbox"/>	<input type="checkbox"/>
						<input type="checkbox"/>	<input type="checkbox"/>
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T.P Glenn, et al., DESIGNING MEMS INTO SYSTEMS:PACKAGING ISSUES, http://www.ecnmag.com , 4 Pgs.	
EXAMINER	DATE CONSIDERED

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		APPLICANT Terry Tarn				
		FILING DATE 10/30/03		GROUP 2826		
<i>Sheet 4 of 4</i>						
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
						YES
						<input type="checkbox"/> <input type="checkbox"/>
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)						
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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Sheet

5 of 10

Complete if Known

Application Number	10/698,656
Filing Date	10/30/03
First Named Inventor	Terry Tarn
Group Art Unit	2820
Examiner Name	Victor Mandala

Attorney Docket Number P106-US

OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No. 1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T ²
	CA	ESPINOSA et al., "Identification of Residual Stress State in an RF-MEMS Device", MTS Systems Corporation white paper (May 2000).	
	CB	FRANKA et al., "Solder Bump Technology: Present and Future", Semiconductor Fabtech (May 1995).	
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	CJ	MOORE, D., "Automation Requirements for Die Bonding Process", Electronics Engineer (July 2000).	
	CK	TSAU, C., "Wafer-Level Packaging", MIT Microsystems Technology Laboratories Annual Report (May 2000), p. 49.	

Examiner
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		P106-US	10/698,656
		APPLICANT Terry Tarn	
		FILING DATE 10/30/03	GROUP 2826

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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						YES	NO
						<input type="checkbox"/>	<input type="checkbox"/>
						<input type="checkbox"/>	<input type="checkbox"/>

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

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Attorney Docket No. P106-US -Serial No. 10/698,656

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